PRODUCT DATA SHEET
TACFlux® 26S

Introduction

TACFlux® 26S is a NIA halogen-free, no-clean rework flux, which is designed to leave a completely benign, clear residue. The reduction in residue optimizes underfill adhesion and decreases possible outgassing during underfill cure.

Features

- Halogen-free – no intentionally added (NIA) halogens
- Suitable for Pb-free alloys
- Compatible with underfills
- Dipping with minimal bridging
- Designed for rework applications
- Low residue
- Bubble-free (airless) packaging

Properties

Property	Value	Test Method
Flux Classification	REL0	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Color	Light Yellow	Visual
Typical Viscosity	13kcps	Brookfield HB DVII+-CP (20rpm)
SIR (Ohms)	Pass (>10^8 after 7 days @ 85°C & 85% RH)	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Acid Value	39mg KOH/g	Titration
Shelf Life	6 months @ 0 to 30°C	Viscosity Change/ Microscope Examination
Typical Post Reflow Residual Weight	<10%	TGA

All information is for reference only. Not to be used as incoming product specifications.

Application

TACFlux® 26S is intended to be used in a nitrogen reflow environment of 100ppm oxygen or less. Some applications can utilize this material in an air environment, although best results will be obtained in an inert atmosphere. **TACFlux® 26S** can be used on many surface finishes including immersion Ag, Cu-OSP, AuNi, and AuPdNi, and is compatible with all standard flip-chip solders.

Compatibility

The compatibility of flip-chip flux residues with epoxy-based capillary underfills is determined by measuring the shear strength of the interface between the post-reflow flux and the cured underfill. The best results for **TACFlux® 26S** have been observed with both amine- and acid anhydride-based capillary underfill chemistries.

Cleaning

TACFlux® 26S is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner. Please contact an Indium Corporation Technical Service Engineer for recommendations of cleaners to suit your process needs.

Storage

TACFlux® 26S syringes and cartridges should be stored tip down at 0° to 30°C for maximum shelf life. **TACFlux® 26S** should be allowed to reach ambient temperature before use.

Packaging

TACFlux® 26S is most commonly available in 10 and 30cc syringes. Other packaging can be provided to meet specific requirements.

From One Engineer To Another®

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Technical Support

Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of materials science and semiconductor packaging process applications.

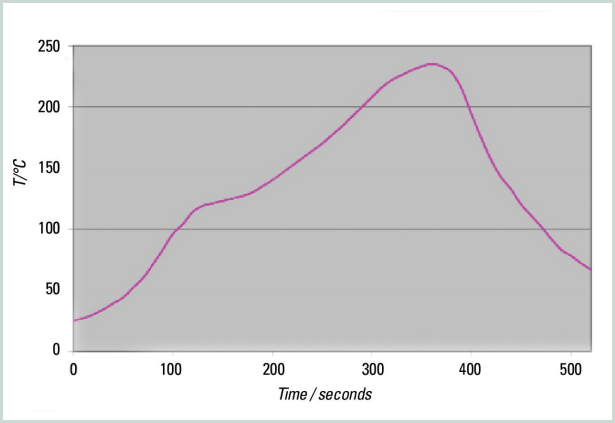
Safety Data Sheets

The SDS for this product can be found online at http://www.indium.com/sds

Reflow

Recommended Profile:

Reflow Profile: SAC305



A short preheat (150°-160°C) for less than 45 seconds may be used to reduce voiding. The profile should ideally be a linear ramp at 2-3°C/second up to 20-30°C above solidus temperature, with a slow cool down afterwards of -0.5 to -0.2°C, and a minimum time above liquidus of 60 seconds.

Contact our engineers today: askus@indium.com
Learn more: www.indium.com

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